

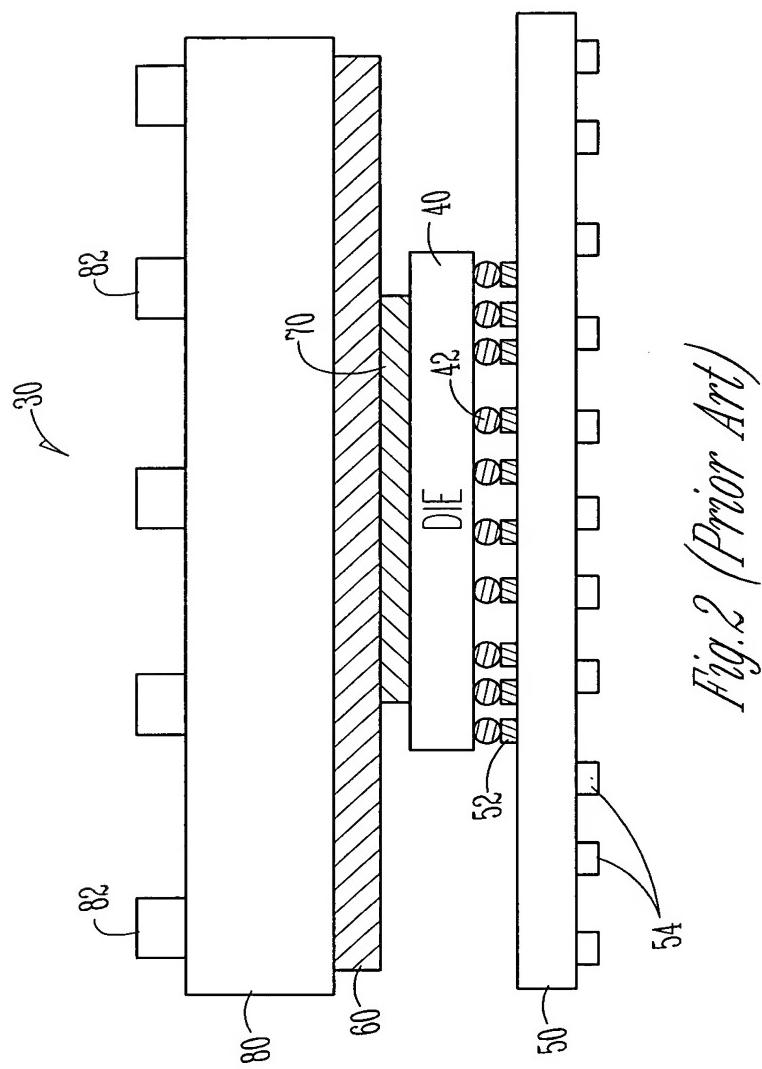
Fig. 1

TITLE: DIAMOND HEAT SPREADING AND COOLING TECHNIQUE FOR INTEGRATED CIRCUITS

INVENTORS NAME: Michael O'Connor et al.

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*Fig. 2 (Prior Art)*

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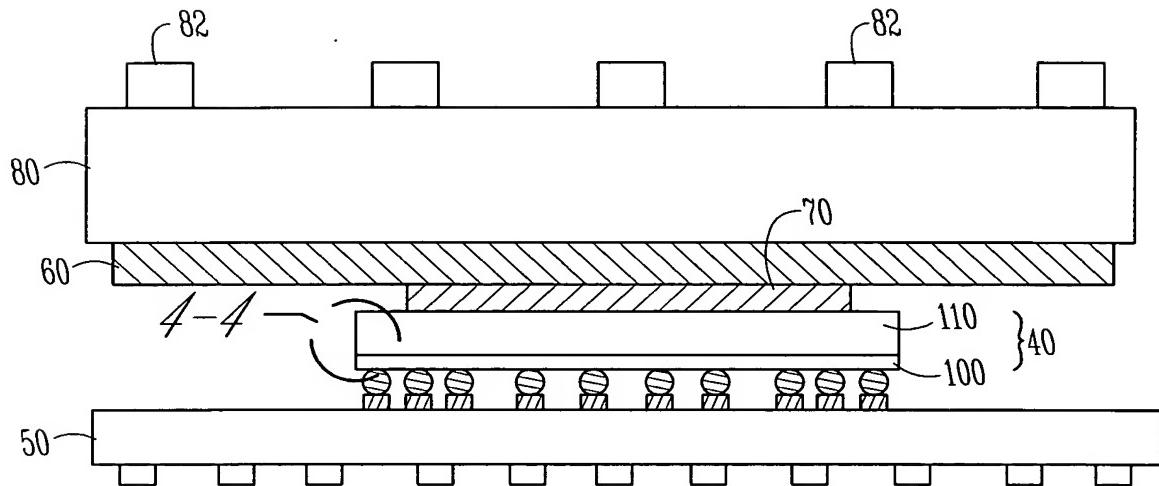


Fig. 3a

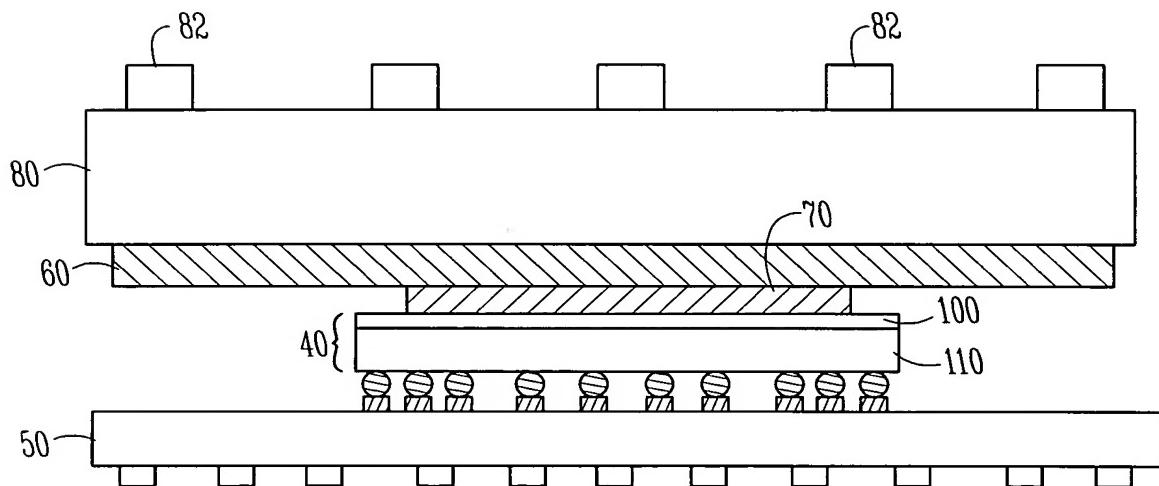
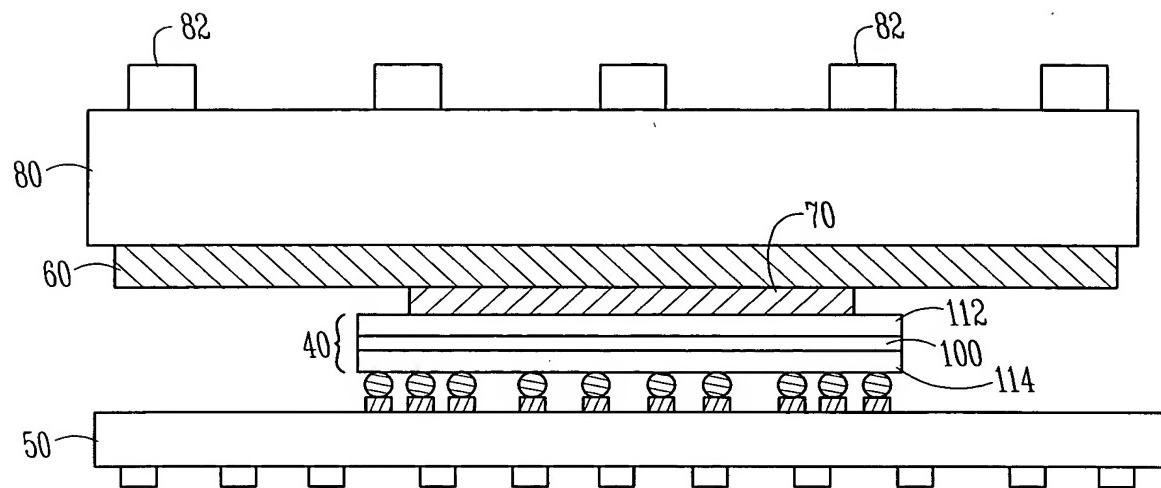
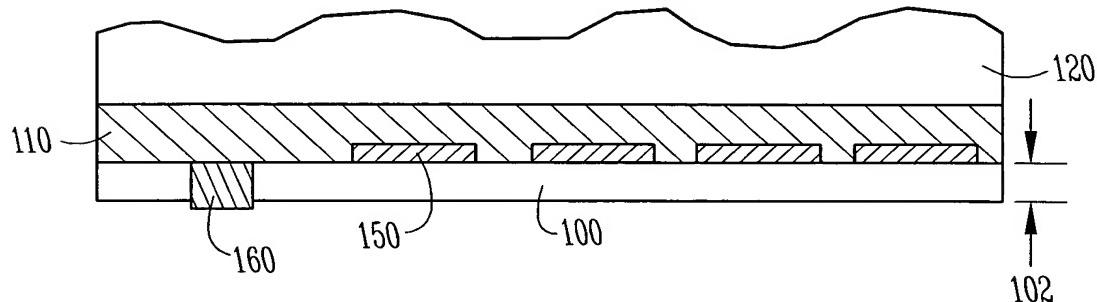


Fig. 3b

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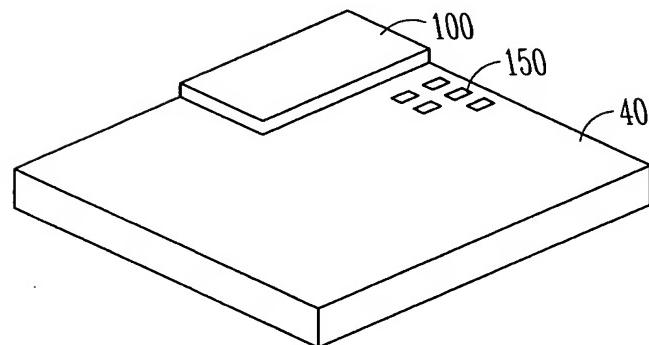


*Fig. 3c*

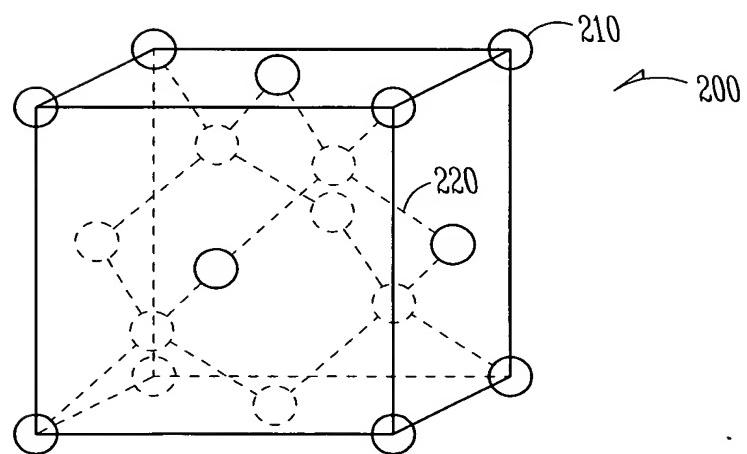


*Fig. 4*

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*Fig. 5*



*Fig. 6*

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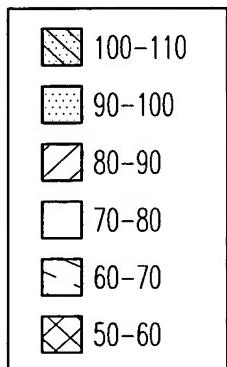
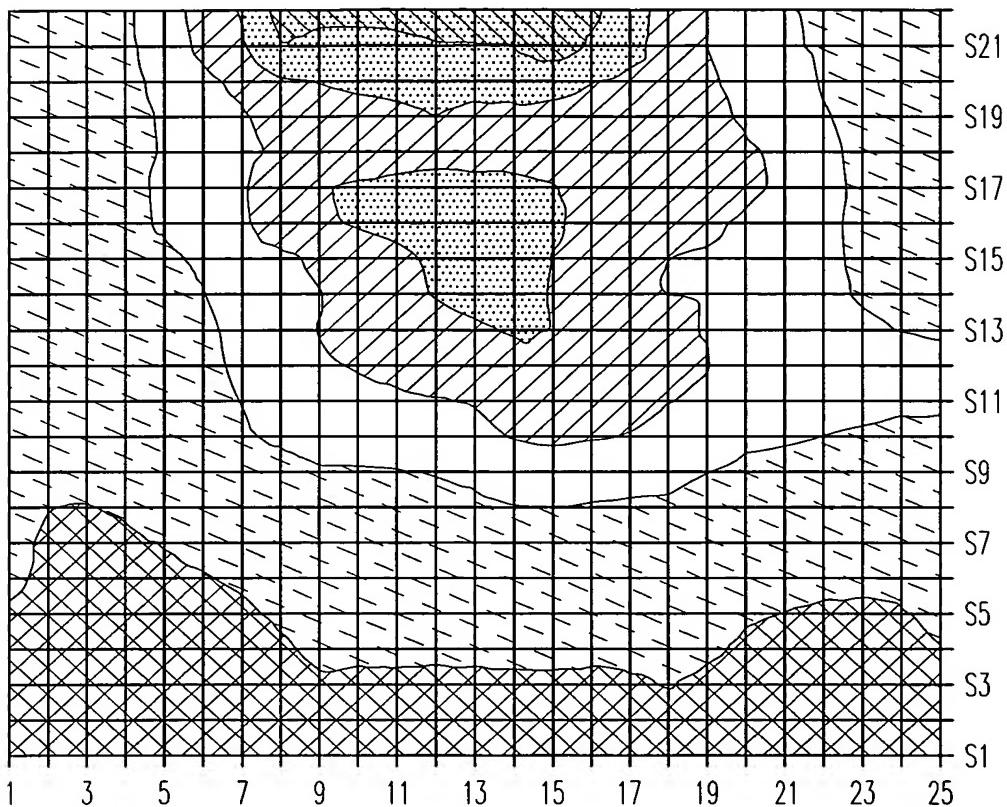


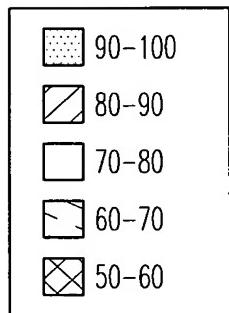
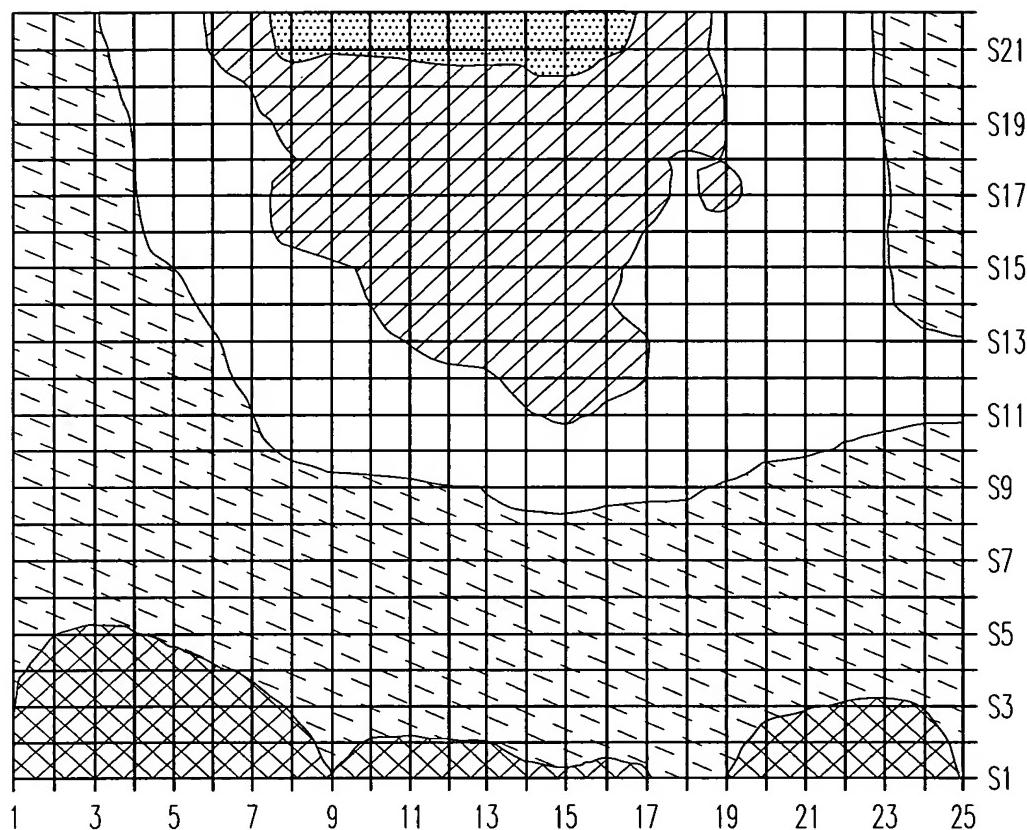
Fig. 7a

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*Fig. 7b*